Title (en)

Flexible rod light device formed of chip on board based LED lamps and manufacturing method thereof

Title (de)

Biegsame Lichtleiste mit LED-Lampen des Chip-auf-LPL-Types und deren Herstellungsverfahren

Title (fr)

Bande lumineuse flexible comprenant des lampes-diodes du type puce-sur-panneau et procédé de fabrication d'une telle bande

Publication

EP 1357331 A3 20060426 (EN)

Application

EP 03252581 A 20030424

Priority

CN 02117197 A 20020425

Abstract (en)

[origin: EP1357331A2] Flexible rod light device containing a string of chip on board (C.O.B.) based LED lamps (20) and manufacturing method thereof are disclosed. The device comprises an inner layer (10) including two parallel upward flanges (12,13) on sides and a lengthwise top groove (11) between the flanges; a string of C.O.B. based LED lamps (20) comprising a plurality of series connected units each including a C.O.B. based LED lamp (21) secured on the groove (11) and between the flanges (12,13), one or more conductor means (23), and a resistor (22); a pair of main wires (31,32) parallel disposed within the flanges (12,13); and a jacket (40) wrapped up the inner layer (10) and the string of lamps (20). All lamps are secured and have the same orientation for achieving an increased illumination.

IPC 8 full level

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CPC (source: EP KR US)

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Citation (search report)

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